SH1517; SH1517P

FEATURES

- Requires very few external components
- · High output power
- · Fixed gain
- · Good ripple rejection
- · Mute/standby switch
- AC and DC short-circuit safe to ground and V_P
- · Thermally protected
- Reverse polarity safe
- Capability to handle high energy on outputs (V_P = 0 V)
- No switch-on/switch-off plop
- Electrostatic discharge protection.

GENERAL DESCRIPTION

The SH1517 is an integrated class-B dual output amplifier in a plastic single in-line medium power package with fin (SIL9MPF) and a plastic heat-dissipating dual in-line package (HDIP18). The device is primarily developed for multi-media applications.

QUICK REFERENCE DATA

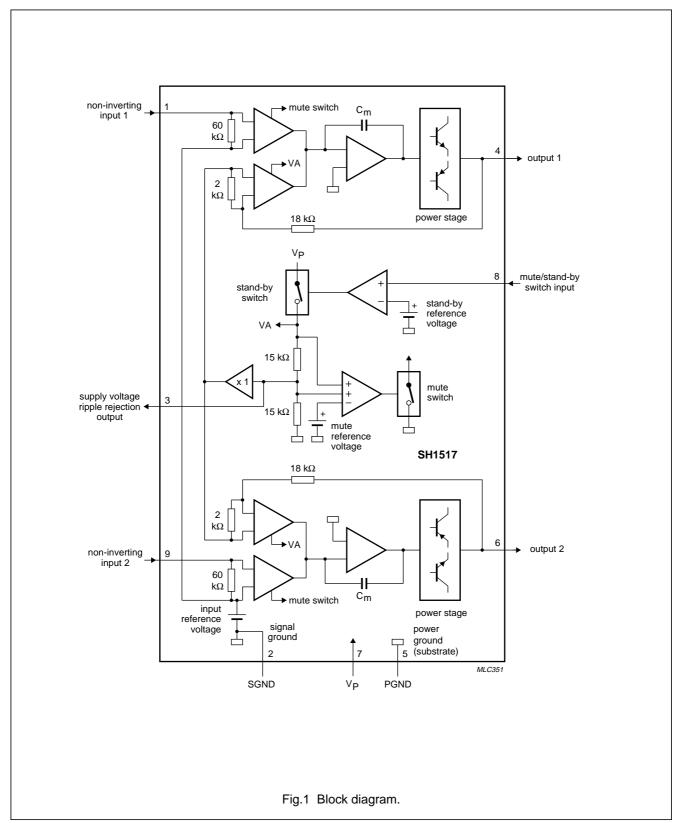
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage		6.0	14.4	18.0	V
I _{ORM}	repetitive peak output current		_	_	2.5	Α
I _{q(tot)}	total quiescent current		_	40	80	mA
I _{sb}	standby current		_	0.1	100	μΑ
I _{sw}	switch-on current		_	_	40	μΑ
Z _I	input impedance		50	_	_	kΩ
Po	output power	$R_L = 4 \Omega$; THD = 0.5%	_	5	_	W
		$R_L = 4 \Omega$; THD = 10%	_	6	_	W
SVRR	supply voltage ripple rejection	f _i = 100 Hz to 10 kHz	48	_	_	dB
$\alpha_{ extsf{cs}}$	channel separation		40	_	_	dB
G _v	closed loop voltage gain		19	20	21	dB
V _{no(rms)}	noise output voltage (RMS value)		_	50	_	μV
T _c	crystal temperature		_	_	150	°C

ORDERING INFORMATION

TYPE		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
SH1517	SIL9MPF	plastic single in-line medium power package with fin; 9 leads	SOT110-1
SH1517P	HDIP18	plastic heat-dissipating dual in-line package; 18 leads	SOT398-1

SH1517; SH1517P

BLOCK DIAGRAM

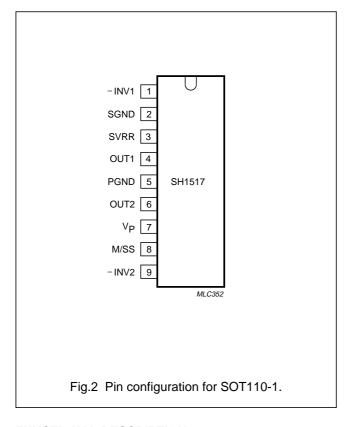


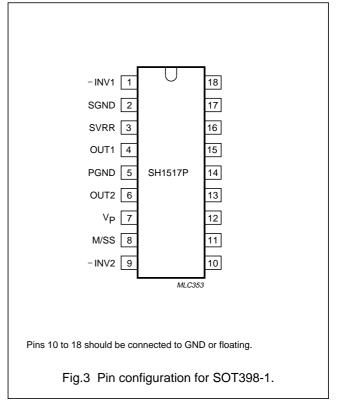


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PINNING

SYMBOL	PIN	DESCRIPTION
-INV1	1	non-inverting input 1
SGND	2	signal ground
SVRR	3	supply voltage ripple rejection output
OUT1	4	output 1
PGND	5	power ground
OUT2	6	output 2
V_P	7	supply voltage
M/SS	8	mute/standby switch input
-INV2	9	non-inverting input 2





FUNCTIONAL DESCRIPTION

The SH1517 contains two identical amplifiers with differential input stages. The gain of each amplifier is fixed at 20 dB. A special feature of the device is the mute/standby switch which has the following features:

- Low standby current (<100 μA)
- Low mute/standby switching current (low cost supply switch)
- Mute condition.

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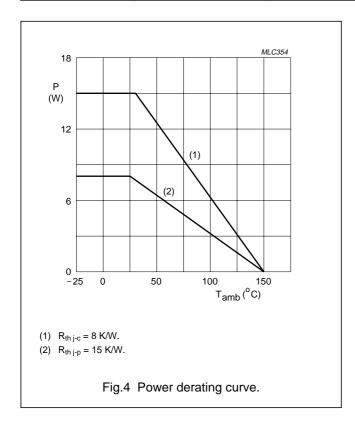
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _P	supply voltage		_	18	V
V _{P(sc)}	AC and DC short-circuit safe voltage		_	18	V
V _{P(r)}	reverse polarity		_	6	V
ERGO	energy handling capability at outputs	$V_P = 0 V$	_	200	mJ
I _{OSM}	non-repetitive peak output current		_	4	Α
I _{ORM}	repetitive peak output current		_	2.5	А
P _{tot}	total power dissipation	see Fig.4	_	15	W
T _{stg}	storage temperature		-55	+150	°C
T _{amb}	operating ambient temperature		-40	+85	°C
T _c	crystal temperature		_	150	°C

THERMAL RESISTANCE

SYMBOL	TYPE NUMBER	PARAMETER	VALUE	UNIT
R _{th j-c}	SH151	thermal resistance from junction to case	8	K/W
R _{th j-p}	SH1517	thermal resistance from junction to pins	15	K/W
R _{th j-a}	SH1517; SH1517P	thermal resistance from junction to ambient	50	K/W



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DC CHARACTERISTICS

 V_P = 14.4 V; T_{amb} = 25 °C; measured in Fig.6; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V _P	supply voltage	note 1	6.0	14.4	18.0	V
I _{q(tot)}	total quiescent current		_	40	80	mA
Vo	DC output voltage		_	6.95	_	V
Mute/standby	switch					
V ₈	switch-on voltage level	see Fig.5	8.5	_	_	٧
Mute condition	n					
Vo	output signal in mute position	$V_{I(max)} = 1 \text{ V; } f_i = 20 \text{ Hz to } 15 \text{ kHz}$	_	_	2	mV
Standby cond	lition					
I _{sb}	DC current in standby condition		_	_	100	μΑ
V _{sw}	switch-on current		_	12	40	μΑ

Note

1. The circuit is DC adjusted at V_P = 6 to 18 V and AC operating at V_P = 8.5 to 18 V.

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AC CHARACTERISTICS

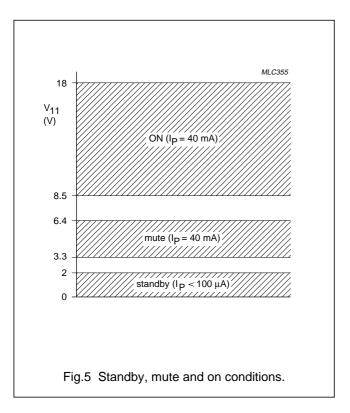
 V_P = 14.4 V; R_L = 4 Ω ; f = 1 kHz; T_{amb} = 25 °C; measured in Fig.6; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Po	output power	THD = 0.5%; note 1	4	5	_	W
		THD = 10%; note 1	5.5	6.0	_	W
THD	total harmonic distortion	P _o = 1 W	_	0.1	_	%
f _{lr}	low frequency roll-off	at -3 dB; note 2	_	45	_	Hz
f _{hr}	high frequency roll-off	at -1 dB	20	-	_	kHz
G _v	closed loop voltage gain		19	20	21	dB
SVRR	supply voltage ripple rejection	note 3				
	on		48	_	_	dB
	mute		48	_	_	dB
	standby		80	_	_	dB
Z _i	input impedance		50	60	75	kΩ
V _{no}	noise output voltage					
	on	$R_s = 0 \Omega$; note 4	_	50	_	μV
	on	$R_s = 10 \Omega$; note 4	_	70	100	μV
	mute	note 5	_	50	_	μV
α_{cs}	channel separation	$R_s = 10 \Omega$	40	_	_	dB
ΔG _ν	channel unbalance			0.1	1	dB

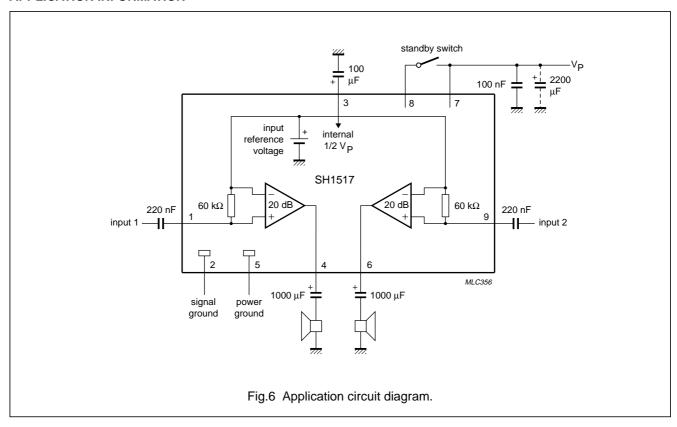
Notes

- 1. Output power is measured directly at the output pins of the IC.
- 2. Frequency response externally fixed.
- 3. Ripple rejection measured at the output with a source impedance of 0 Ω , maximum ripple amplitude of 2 V (p-p) and a frequency between 100 Hz and 10 kHz.
- 4. Noise voltage measured in a bandwidth of 20 Hz to 20 kHz.
- 5. Noise output voltage independent of R_s ($V_I = 0 V$).

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APPLICATION INFORMATION

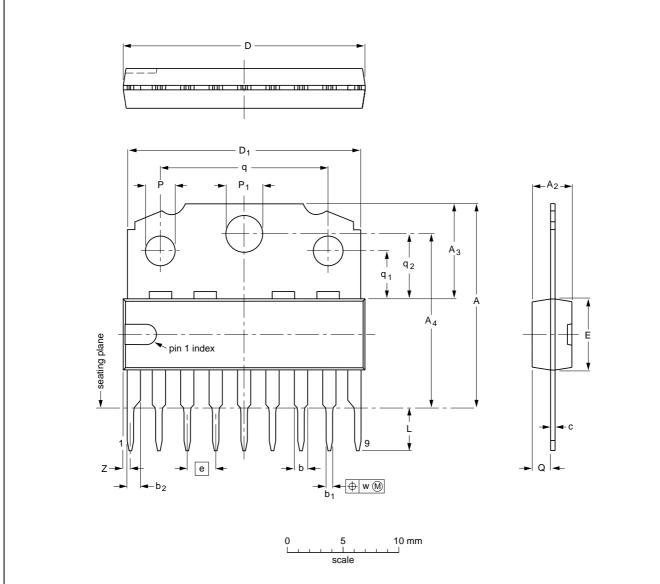


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PACKAGE OUTLINES

SIL9MPF: plastic single in-line medium power package with fin; 9 leads

SOT110-1



DIMENSIONS (mm are the original dimensions)

UNIT	Α	A ₂ max.	A ₃	A ₄	b	b ₁	b ₂	С	D ⁽¹⁾	D ₁	E ⁽¹⁾	е	L	Р	P ₁	Q	q	q 1	q ₂	w	Z ⁽¹⁾ max.
mm	18.5 17.8	3.7	8.7 8.0	15.8 15.4	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	3.9 3.4	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.25	1.0

Note

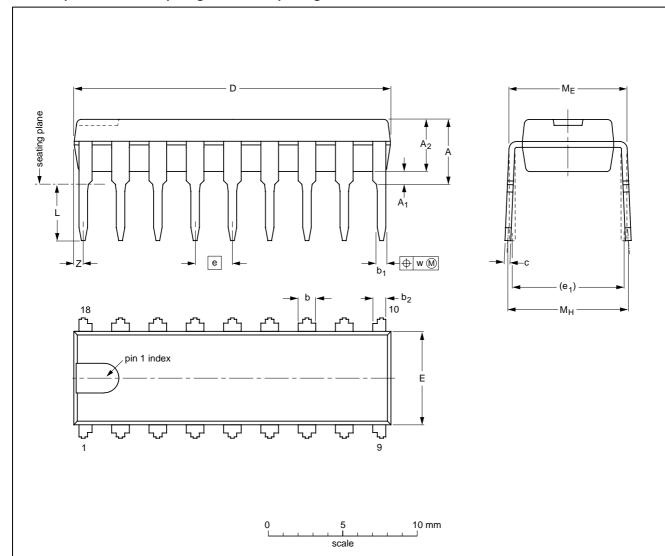
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT110-1				$ \ \ \bigoplus \big($	92-11-17 95-02-25

SH1517; SH1517P

HDIP18: plastic heat-dissipating dual in-line package; 18 leads

SOT398-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.67 0.50	1.05 0.75	0.47 0.38	21.85 21.35	6.5 6.2	2.54	7.62	3.9 3.1	8.32 8.02	8.7 7.7	0.25	1.0
inches	0.19	0.02	0.15	0.06 0.04	0.03 0.02	0.04 0.03	0.02 0.01	0.87 0.84	0.26 0.24	0.10	0.30	0.15 0.12	0.33 0.32	0.34 0.30	0.01	0.04

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT398-1					94-04-13 95-01-25

2 × 6 W stereo power amplifier

SH1517; SH1517P

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact

with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.